



SBR1U40LP

## 1.0A SBR<sup>®</sup> SUPER BARRIER RECTIFIER

### **Features**

- Ultra Low Forward Voltage Drop
- Excellent High Temperature Stability
- Patented Super Barrier Rectifier Technology
- · Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead Free By Design, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Notes 2 & 3)

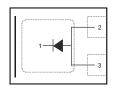
### **Mechanical Data**

- Case: X1-DFN1411-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Lead Frame.
   Solderable per MIL-STD-202, Method 208
- Weight: 2.35mg (approximate)

#### X1-DFN1411-3







Top View

**Bottom View** 

Top View Internal Schematic

### Ordering Information (Note 4)

Part Number	Case	Packaging
SBR1U40LP-7	X1-DFN1411-3	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
- 2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 4. For packaging details, go to our website at http://www.diodes.com

# **Marking Information**



<u>D</u>4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: U = 2007)
 M = Month (ex: 9 = September)

### Date Code Key

Year	2007	20	08	2009	2010	20	11	2012	2013	20	14	2015
Code	<u>U</u>	\	/	W	Х	,	Y	Z	Α	I	3	С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage (Note 5) Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Rectified Output Current (See Figure 1)	I <sub>0</sub>	1.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	5	А
Non-Repetitive Peak Forward Surge Current 15s Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	2.6	А

### Thermal Characteristics

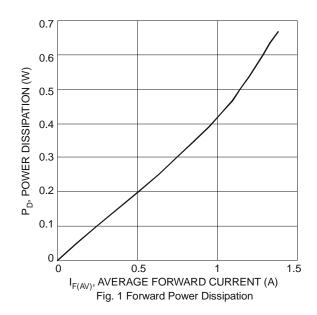
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_{D}$	400	mW
Maximum Thermal Resistance Junction to Ambient (Note 6)	$R_{ heta JA}$	190	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

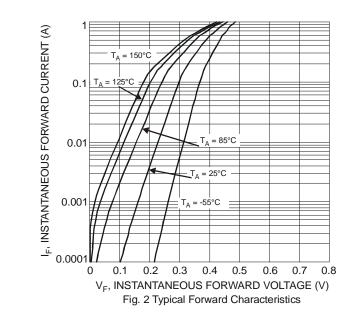
## Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
	V <sub>F</sub>	-	0.39	0.42	V	$I_F = 0.5A, T_J = 25^{\circ}C$
Forward Voltage Dren		-	0.46	0.49		$I_F = 1.0A, T_J = 25^{\circ}C$
Forward Voltage Drop		-	0.34	0.37		$I_F = 0.5A, T_J = 125^{\circ}C$
		-	0.43	0.47		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C
Lookaga Current (Note 7)	I <sub>R</sub>	-	-	50	μΑ	$V_R = 40V, T_J = 25^{\circ}C$
Leakage Current (Note 7)		-	-	100	mA	$V_R = 40V, T_J = 125^{\circ}C$

Notes:

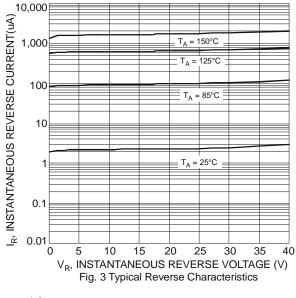
- 5.  $V_{RRM}$  characteristic is base on 1mA leakage current test condition 6. Device mounted on Polymide substrate 1" x 1", 2oz. Copper double sided PCB board.
- 7. Short duration pulse test used to minimize self-heating effect.

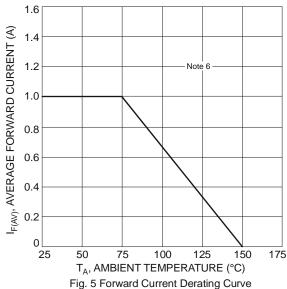




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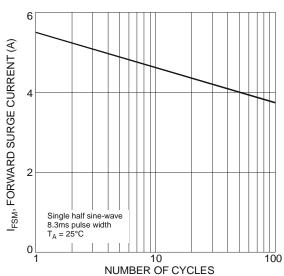


Fig. 7 Forward Surge Current vs. Number of Cycles

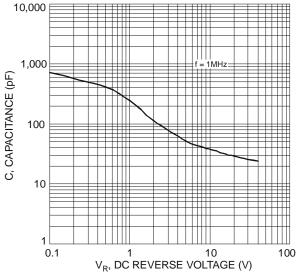
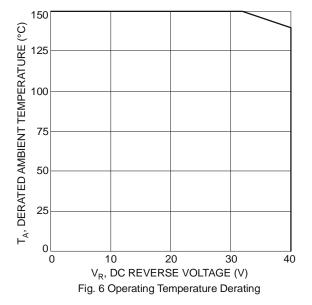
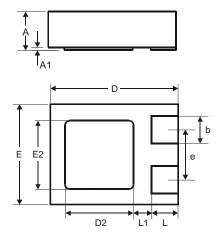


Fig. 4 Total Capacitance vs. Reverse Voltage



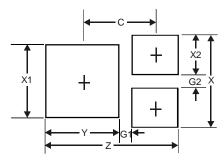


# **Package Outline Dimensions**



X1-DFN1411-3						
Dim	Min	Max	Тур			
Α	0.47	0.53	0.50			
A1	0	0.05	0.02			
b	0.25	0.35	0.30			
D	1.35	1.475	1.40			
D2	0.65	0.85	0.75			
Е	1.05	1.175	1.10			
E2	0.65	0.85	0.75			
е	_	_	0.55			
L	0.225	0.325	0.275			
L1	_		0.20			
All Dimensions in mm						

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	1.38
G1	0.15
G2	0.15
Х	0.95
X1	0.75
X2	0.40
Υ	0.75
C	0.76



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